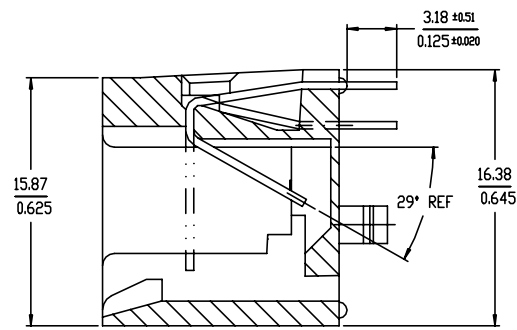
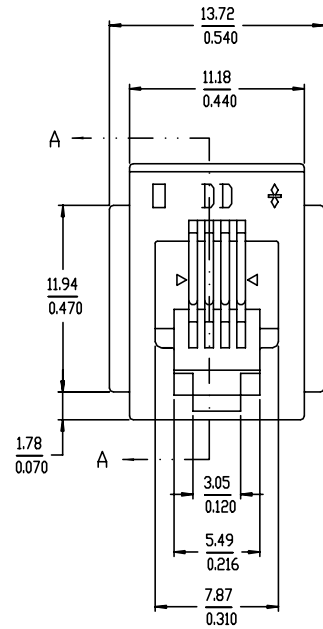
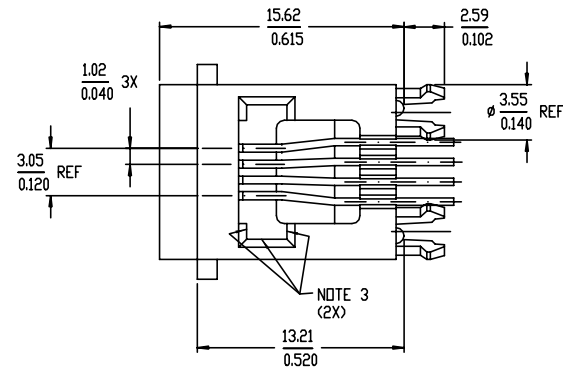
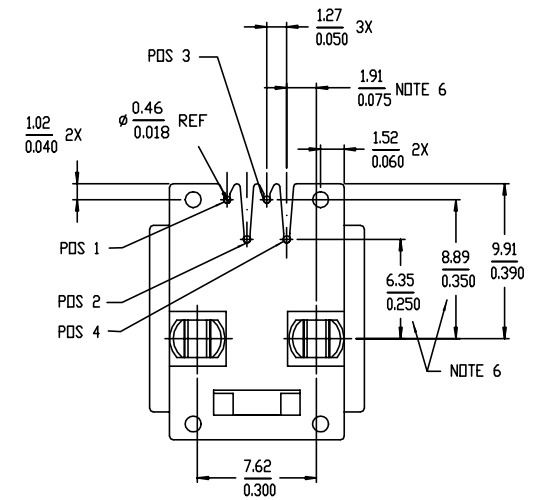


PRODUCT NO.
SEE CHART

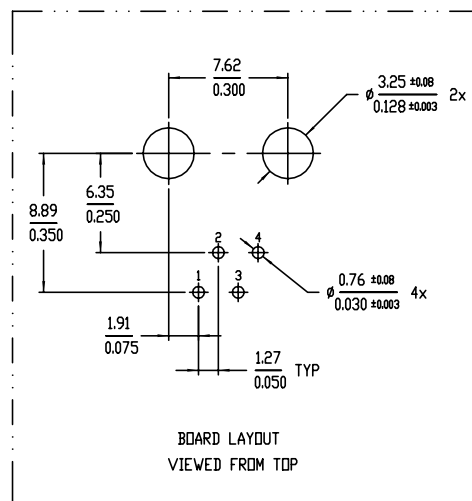
SECTION A-A



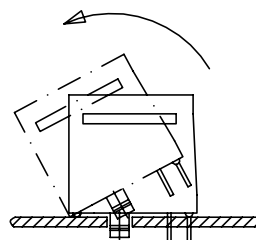
mat'l. code				surface ISO1302		tolerance ISO1101 ISO406	projection mm	product family MOD JACK			
ltr ecn nodr				date		tolerances unless otherwise specified	mm	4 POS VERT. SNAP PEG PCB III MOD JACK ASSY			
K	S00022	LOW	01/25/00			0.X±0.3					
L	N04-0102	YS	11/23/04			0.XX±0.15					
M	N08-0097	SH MMD	09/25/08			0.XXX±0.05	scale 2.0				
N	N08-0170	SH MMD	10/09/08	dr	M CHENG	7/13/01		dwg no			
P	ELX-N-010673	SH MMD	3/14/12	enr	M CHENG	7/13/01		sheet 1 of 2			
				chr	M CHENG	7/13/01		size			
				appd	J HSIA	7/20/01		A4			
sheet				revision	P	P		type			
index				sheet	1	2		Product Customer Drawing			

PRODUCT NO.	POSITIONS LOADED	CONTACT PLATING	NOTES
90511-001 -001LF -001HLF	ALL	5u" Au + high performance lubricant	BLACK
-002 -002LF -002HLF	ALL	5u" Au + high performance lubricant	BLACK
-003 -003LF	ALL	5u" Au + high performance lubricant	GREY
-004 -004LF	ALL	5u" Au + high performance lubricant	GREY
-005 -005LF -005HLF	ALL	50u" / 1.27u GXT	BLACK

LEAD FREE PRODUCT NO.
MEETS PIP PROCESS PRODUCT NO.



DIRECTION OF DISMOUNT



JACK DISMOUNT METHOD

DETAIL A
NOTE 5

PRODUCT NO.	POSITIONS LOADED	CONTACT PLATING	REMARKS
90511-101 -101LF -101HLF	ALL	5u" Au + high performance lubricant	NOT TOOLED
-102 -102LF -102HLF	ALL	5u" Au + high performance lubricant	NOT TOOLED

NOTES :

- P/NO WITH DASH 0XX -NORMAL WAVE SOLDERING APPLICATION.
P/NO WITH DASH 1XX -IR REFLOW APPLICATION (NOT TOOLED).
- PACKAGING SPEC. BUS-14-164.
- SCRATCH MARKS ACCEPTABLE ON THESE SURFACES.
- JACK IS FOR 1,57//,062 THICK PCB.
- SHOULD THE JACK NEED TO BE DISMOUNTED FROM THE PCB, PLS REMOVE JACK AS PER RECOMMENDED METHOD HEREIN. (DETAIL A)
NIPPING THE LEGS OF THE PEG TOGETHER IS DISALLOWED, OTHERWISE LEG BREAKAGE MAY OCCUR.
- THESE DIMENSIONS ARE TAKEN FROM THE TOP OF THE PEG.
- THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60mm MINIMUM THICK CIRCUIT BOARD.
- IF LF P/N PACKAGING MEETS GS-14-920 SPECIFICATION.
- EQUIVALENT THICKNESS Au AND GXT PLATING HAVE SAME FUNCTION AND THEY ARE ALTERNATIVE BY THE CUSTDEMR .

mat'l. code				surface  tolerance		projection 		product family							
				ISO1302		ISO1101 ISO406		MOD JACK							
l t r e c n n o d r				date				tolerances unless otherwise specified				title			
K	S00022	LOW	01/25/00	angle line at	0.X±0.3		 mm	4 POS VERT. SNAP PEG PCB III MOD JACK ASSY							
L	N04-0102	YS	11/23/04		0.XX±0.15										
M	N08-0097	SH MMD	09/25/08		0°±2'									0.XXX±0.05	
				0°±2'		scale 2.0									
N	N08-0170	SH MMD	10/09/08	dr	M CHENG	7/13/01		dwg no		sheet 2 of 2		size			
P	ELX-N-010673	SH MMD	3/14/12	engr	M CHENG	7/13/01		90511		A4					
				chr	M CHENG	7/13/01									
				appd	J HSIA	7/20/01									
sheet		revision													
index		sheet													